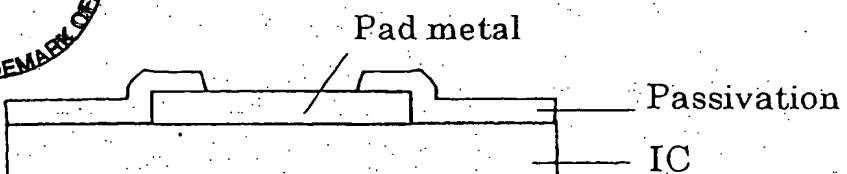
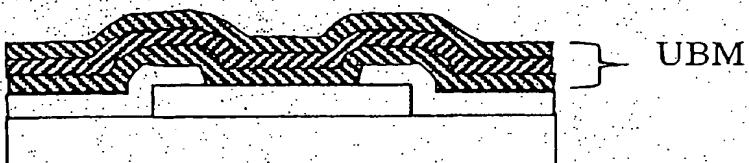


ATTACHMENT A

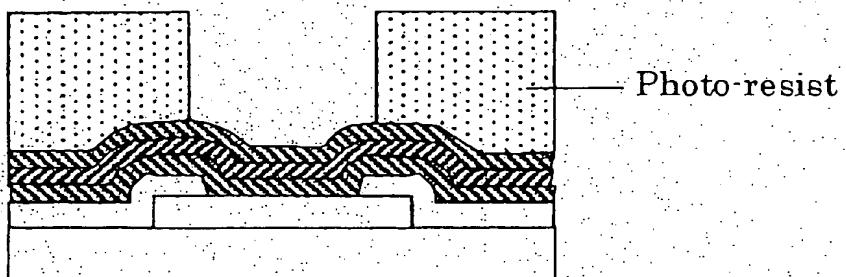
page 1 of 2



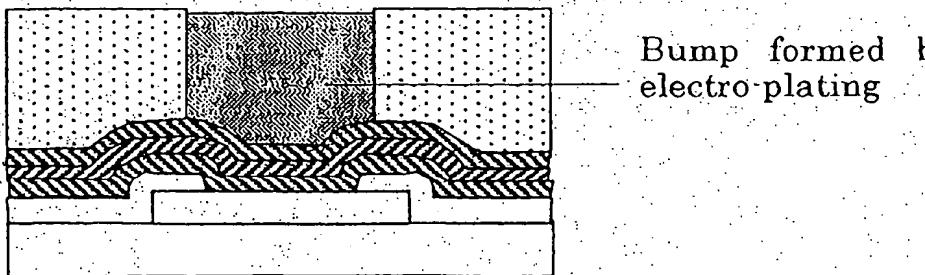
A. Cross section of IC electrode pad



B. UBM deposition

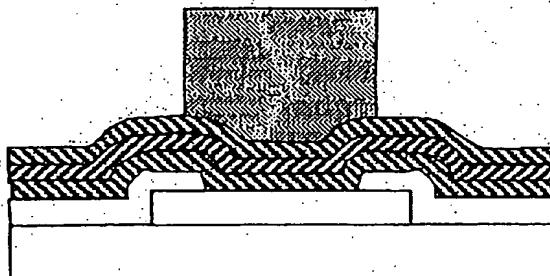


C. photo-lithographic process

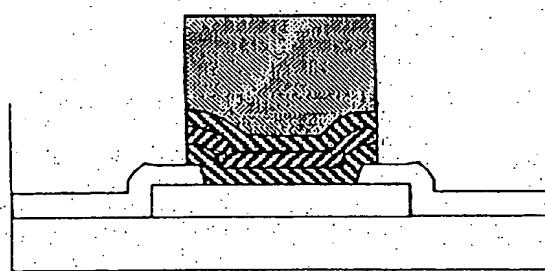


D. Bump formation by electro-plating

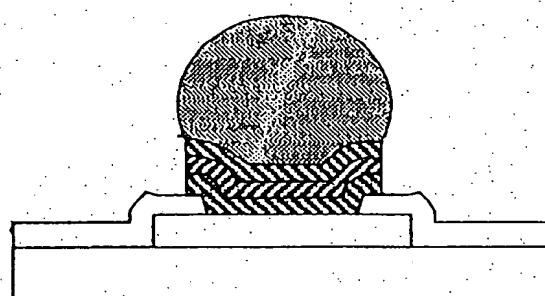
*page 2 of 2*



E. Removing photo-resist



F. Etching of UBM



G. Reflow process